

January 7, 1998

CHARACTERISTICS (@ 25°C unless otherwise specified)

	Symbol	1N5614 S2M	1N5616 S4M	1N5618 S6M	1N5620 S8M	1N5622 S0M	Unit
Average forward current (sine wave) - max. pcb mounted; $T_A = 55^\circ\text{C}$ - max. $L = 3/8"$; $T_L = 55^\circ\text{C}$	$I_F(\text{AV})$ $I_F(\text{AV})$	←		1.0	→		A A
I^2t for fusing ($t = 8.3\text{ms}$) max.	I^2t	←		5.0	→		A^2S
Forward voltage drop max. @ $I_F = 1.0\text{A}$, $T_j = 25^\circ\text{C}$	V_F	←		1.1	→		V
Reverse current max. @ V_{RWM} , $T_j = 25^\circ\text{C}$ @ V_{RWM} , $T_j = 100^\circ\text{C}$	I_R I_R	←		0.5 25	→		μA μA
Reverse recovery time max. 0.5A I_F to 1.0A I_R . Recovers to 0.25A I_{RR} .	t_{rr}	←		2.0	→		μS
Junction capacitance typ. @ $V_R = 5\text{V}$, $f = 1\text{MHz}$	C_j	←		23	→		pF
Thermal resistance - junction to lead Lead length = 0.375"	$R_{\theta\text{JL}}$	←		36	→		$^\circ\text{C/W}$
Lead length = 0"	$R_{\theta\text{JL}}$	←		7	→		$^\circ\text{C/W}$
Thermal resistance - junction to amb. on 0.06" thick pcb. 1 oz. copper.	$R_{\theta\text{JA}}$	←		95	→		$^\circ\text{C/W}$

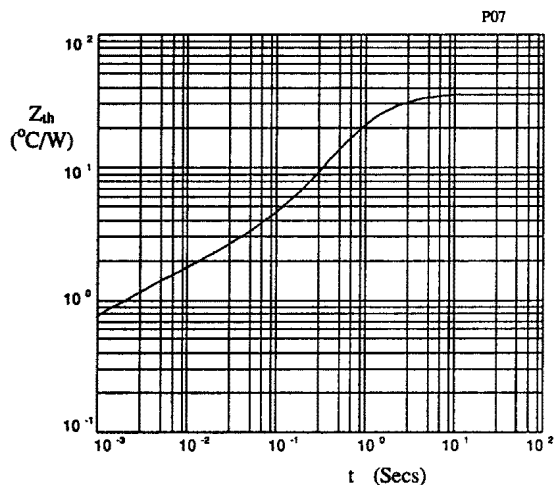


Fig 1. Transient thermal impedance characteristic.

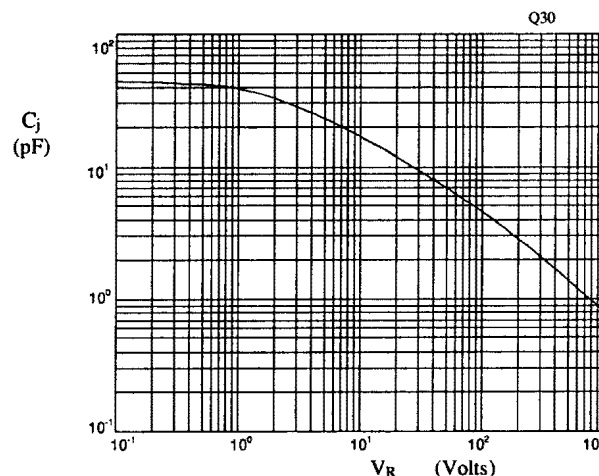


Fig 2. Typical junction capacitance as a function of reverse voltage.

January 7, 1998

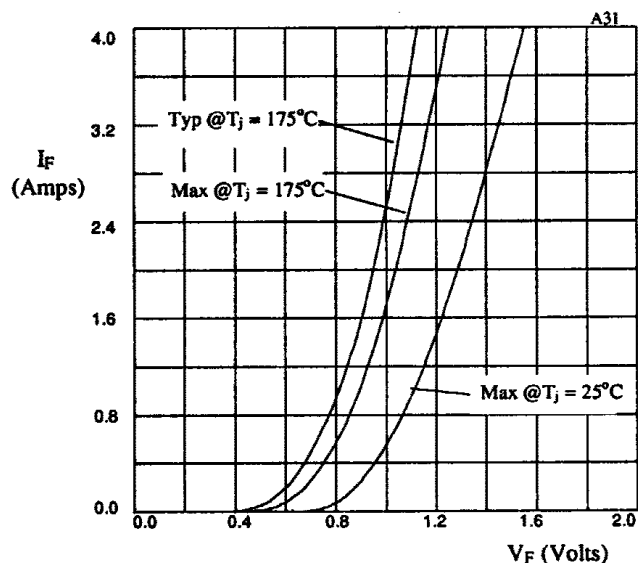


Fig 3. Forward voltage drop as a function of forward current.

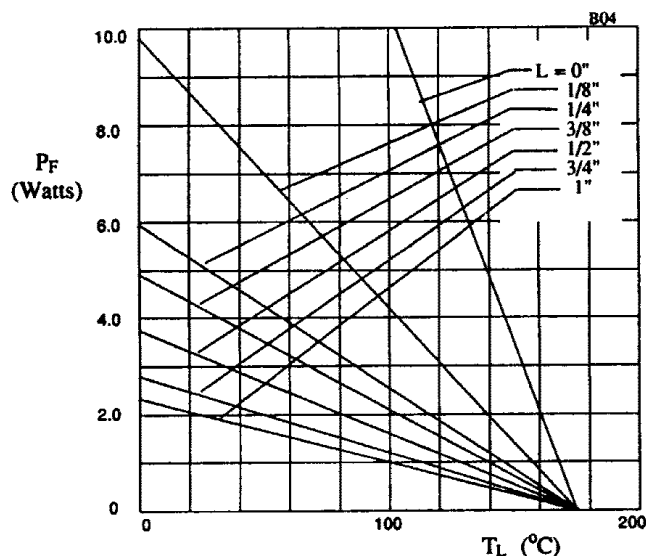


Fig 4. Maximum power versus lead temperature.

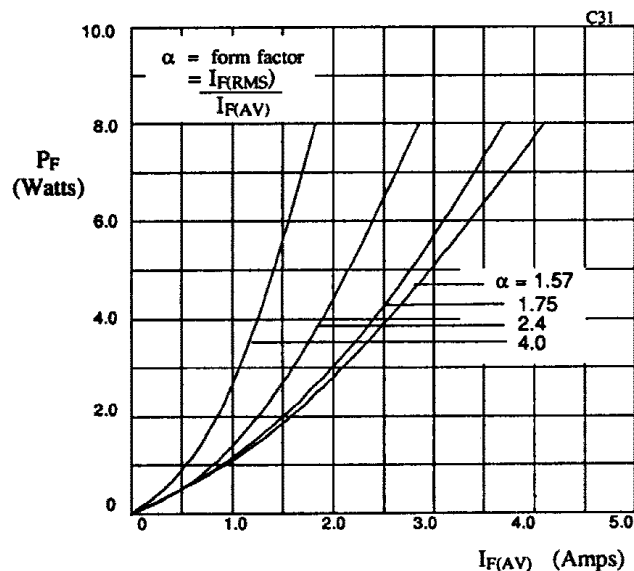


Fig 5. Forward power dissipation as a function of forward current, for sinusoidal operation.

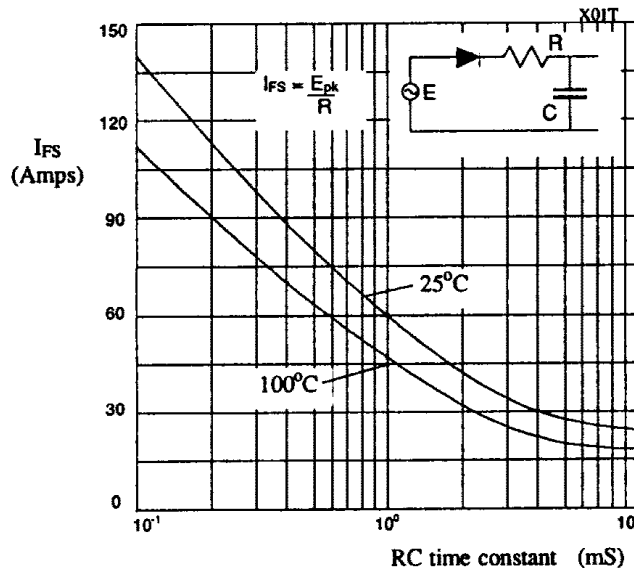


Fig 6. Maximum ratings for capacitive loads.